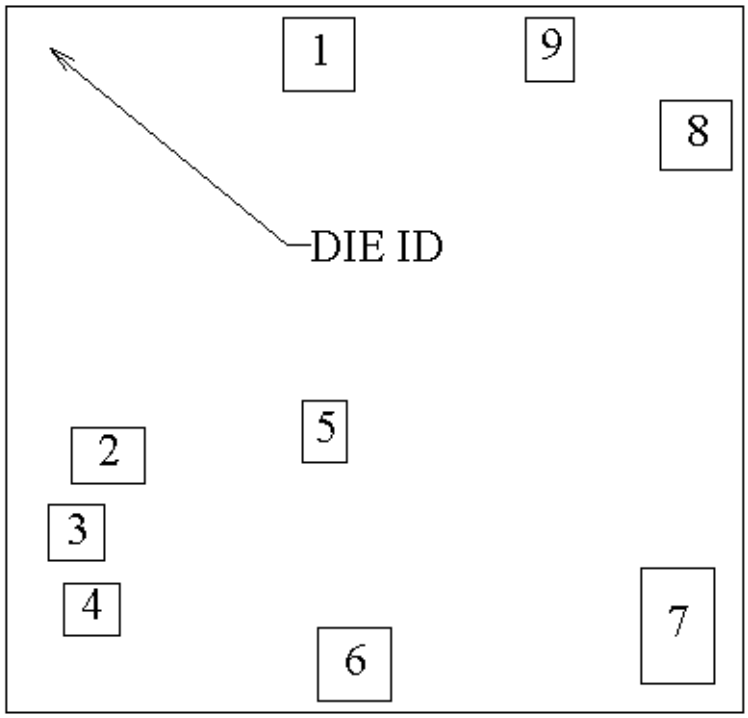
National Semiconductor
The Sight & Sound of Information

DPBU
Die Datasheet

LM136-5.0 MD8 MW8
VOLTAGE REFERENCE DIODE

March 01,2004

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	136B	Bond Pad Opening Size (min)	117µm x 112µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Bare Back
Die Size (Drawn)	1194µm x 1143µm 47.0mils x 45.0mils	Back Side Connection	Floating or -
Thickness	330µm Nominal		
Min Pitch	626µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
ADJ	1	-91	495	117	x	117
NC	2	-432	-155	117	x	91
NC	3	-483	-282	91	x	91
NC	4	-460	-406	91	x	86
NC	5	-81	-117	71	x	97
+	6	-33	-495	117	x	117
NC	7	491	-432	119	x	188
-	8	521	363	117	x	112
NC	9	284	502	81	x	104

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